



IEEE/SICE SII 2024

International Symposium on System Integration
HA LONG, VIETNAM 8-11th January, 2024



IEEE



Ha Long Bay

IEEE/SICE International Symposium on System Integration (SII) is the symposium series presenting the state of the art and future perspectives of system integration, where industrial experts, researchers, and academics share ideas and experiences surrounding frontier technologies, breakthrough and innovative solutions, and applications.

The IEEE/SICE SII 2024 will be the 16th symposium on system integration. System integration is one of the key technologies and the integration of hardware and software is especially important to solve the industrial or social system problems in the new century. This symposium focuses towards new research and industrial applications of system integration, and discusses approaches and methodologies to improve effectiveness of system integration.

Important Dates:

Proposals for Special Sessions	July. 14 2023
Paper Submission*	Aug. 31, 2023
Workshop Proposal Submission Deadline*	Sep. 15, 2023
Notification of Workshop Proposal Acceptance*	Sep. 30, 2023
Notification of Paper Acceptance	Oct. 1, 2023
Final Paper Submission	Oct. 15, 2023
Late Breaking Results Submission	Oct. 15, 2023
Notification of Late Breaking Results Acceptance	Oct. 29, 2023

* Firm deadlines, no further extension

All deadlines are 23:59:59 Pacific Time (PT).



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※ All proceedings will be published on IEEE Xplore, and indexed by Web of Science and Scopus.

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